

Title (en)
SEMICONDUCTOR PACKAGE WITH INTEGRATED INTERFERENCE SHIELDING AND METHOD OF MANUFACTURE THEROF

Title (de)
HALBLEITERKAPSELUNG MIT INTEGRIERTER STÖRUNGSABSCHIRMUNG UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
BOÎTIER SEMI-CONDUCTEUR DOTÉ D UN BLINDAGE CONTRE LES INTERFÉRENCES INTÉGRÉ ET SON PROCÉDÉ DE FABRICATION

Publication
EP 2308085 A1 20110413 (EN)

Application
EP 08796999 A 20080731

Priority
US 2008071832 W 20080731

Abstract (en)
[origin: WO2010014103A1] An integrated electromagnetic interference (EMI) shield for a semiconductor module package. The integrated EMI shield includes a plurality of wirebond springs electrically connected between a ground plane in the substrate of the package and a conductive layer printed on the top of the package mold compound. The wirebond springs have a defined shape that causes a spring effect to provide contact electrical connection between the tops of the wirebond springs and the conductive layer. The wirebond springs can be positioned anywhere in the module package, around all or some of the devices included in the package, to create a complete EMI shield around those devices.

IPC 8 full level
H01L 23/552 (2006.01)

CPC (source: EP KR)
H01L 23/48 (2013.01 - KR); **H01L 23/552** (2013.01 - EP); **H01L 23/60** (2013.01 - KR); **H01L 24/16** (2013.01 - EP); **H01L 24/45** (2013.01 - EP); **H01L 24/48** (2013.01 - EP); **H01L 24/73** (2013.01 - EP); **H01L 2224/16225** (2013.01 - EP); **H01L 2224/32225** (2013.01 - EP); **H01L 2224/45144** (2013.01 - EP); **H01L 2224/45147** (2013.01 - EP); **H01L 2224/48091** (2013.01 - EP); **H01L 2224/48227** (2013.01 - EP); **H01L 2224/48644** (2013.01 - EP); **H01L 2224/48844** (2013.01 - EP); **H01L 2224/73265** (2013.01 - EP); **H01L 2224/85205** (2013.01 - EP); **H01L 2224/85411** (2013.01 - EP); **H01L 2224/85444** (2013.01 - EP); **H01L 2224/85447** (2013.01 - EP); **H01L 2924/01015** (2013.01 - EP); **H01L 2924/01047** (2013.01 - EP); **H01L 2924/0105** (2013.01 - EP); **H01L 2924/01079** (2013.01 - EP); **H01L 2924/12042** (2013.01 - EP); **H01L 2924/1421** (2013.01 - EP); **H01L 2924/181** (2013.01 - EP); **H01L 2924/19105** (2013.01 - EP); **H01L 2924/19107** (2013.01 - EP); **H01L 2924/3025** (2013.01 - EP)

C-Set (source: EP)
1. **H01L 2224/73265 + H01L 2224/32225 + H01L 2224/48227 + H01L 2924/00012**
2. **H01L 2224/48644 + H01L 2924/00**
3. **H01L 2924/12042 + H01L 2924/00**
4. **H01L 2924/181 + H01L 2924/00012**
5. **H01L 2224/48091 + H01L 2924/00012**
6. **H01L 2224/45144 + H01L 2924/00014**
7. **H01L 2224/45147 + H01L 2924/00014**
8. **H01L 2224/48091 + H01L 2924/00014**
9. **H01L 2224/85205 + H01L 2224/45147 + H01L 2924/00**
10. **H01L 2224/85205 + H01L 2224/45144 + H01L 2924/00**
11. **H01L 2924/01047 + H01L 2924/00**
12. **H01L 2924/01015 + H01L 2924/00**
13. **H01L 2224/48844 + H01L 2924/00**

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)
AL BA MK RS

DOCDB simple family (publication)
WO 2010014103 A1 20100204; CN 102105981 A 20110622; CN 102105981 B 20131113; EP 2308085 A1 20110413; EP 2308085 A4 20130605; EP 2752872 A1 20140709; EP 2752872 B1 20180627; HK 1159311 A1 20120727; JP 2011529638 A 20111208; JP 5276169 B2 20130828; KR 101533866 B1 20150703; KR 20110039448 A 20110418

DOCDB simple family (application)
US 2008071832 W 20080731; CN 200880130497 A 20080731; EP 08796999 A 20080731; EP 14163096 A 20080731; HK 11113369 A 20111212; JP 2011521084 A 20080731; KR 20117002352 A 20080731